

WAFER BACK SURFACE TREATING METHOD AND DICING SHEET  
ADHERING APPARATUS  
Yuji OKAWA

Appl. No.: Unknown Atty Docket: UNI79.022AUS

FIG. 1

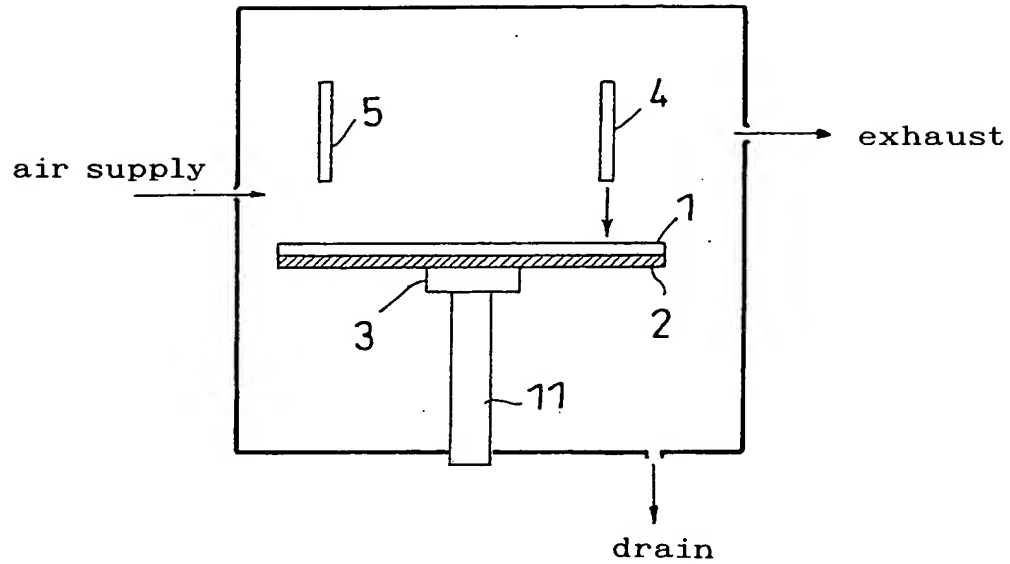


FIG. 2

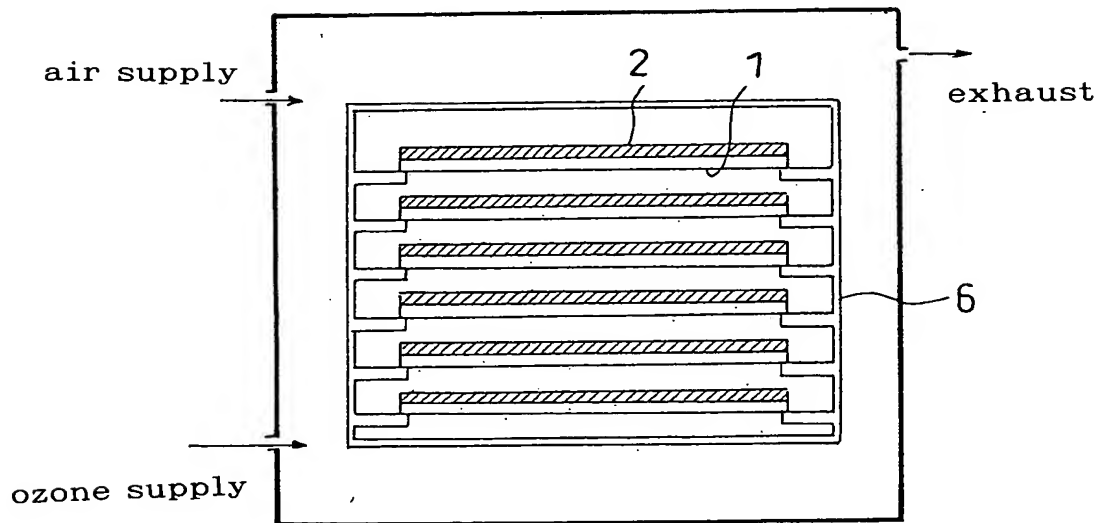


FIG. 3

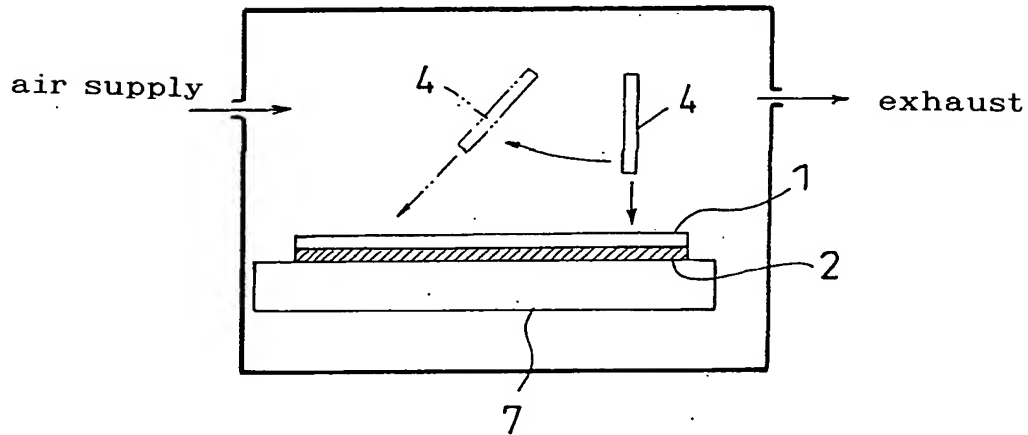
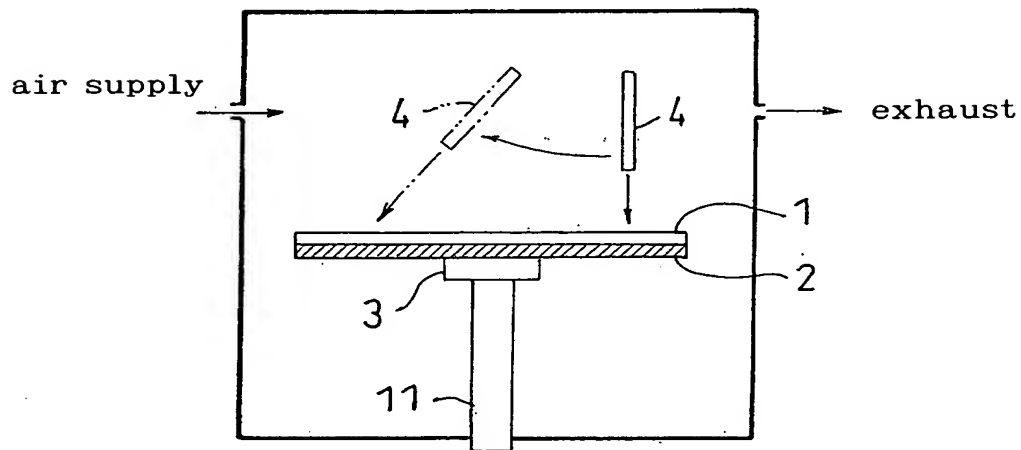


FIG. 4



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FIG. 5

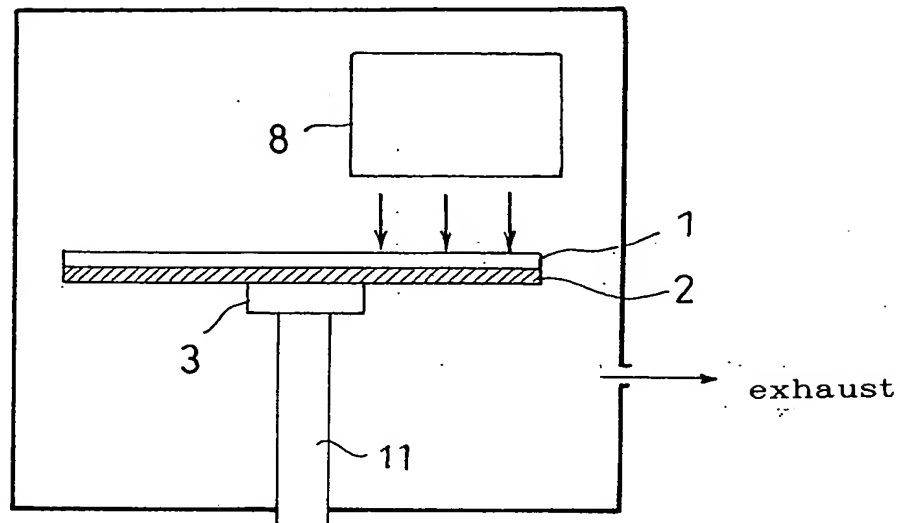


FIG. 6

